

No.	ITEM	Description	Data & Model
1	Material	Brand	SY、ITEQ、KB、NOUYA
2	HDI Construction		1+N+1、 2+N+2、 3+N+3、 4+N+4、 5+N+5、 6+N+6、 anylayer
3	Construction order		N+N、 N+X+N、 1+(N+X+N)+1
4	Layer		1-40Layers
5	Min Pattern Width / Spacing	Unit : mil	2/2
6	Min Mechanical Hole	Unit : mm	0.15mm
7	Min Thickness of Core Board	Unit : mil	2mil
8	Laser Hole	Unit : mm	0.075mm- 0.1mm
9	Min thickness of PP	Unit : mil	2mil
10	Max diameter of resin plug hole	Unit : mm	0.4mm
11	Electroplating to fill holes		Can do it.
12	Electroplating to fill holes size	Unit : mil	3-5mil
13	hole pile pad/hole pile hole/pad hole(VOP)	mil	Can do it.
14	The distance from the wall of via hole to the pattern	mil	7mil
15	Laser drilling hole accuracy	mil	0.025mm
16	Min BGA pad center distance	mil	0.3mm
17	Min SMT	mil	0.25mm
18	Plating hole-filling sag	mil	≤10um

19	Back drilled/countersink hole tolerance	mil	±0.05mm
20	Through-hole plating penetration capacity	Rate	16:1
21	Blind hole plating penetration capacity	Rate	1.2:1
22	BGA min PAD	Unit : mil	0.2
23	Min Buried Hole(Mechanical Hole)	Unit : mil	0.2
24	Min Buried Hole(Laser Hole)	Unit : mil	0.1
25	Min Blind Hole(Laser Hole)	Unit : mil	0.1
26	Min Blind Hole(Mechanical Hole)	Unit : mil	0.2
27	Minimum spacing between laser blind hole and mechanical buried hole	Unit : mil	0.2
28	Min Laser Hole	Unit : mil	0.10(depth≤55um)、0.13(depth≤100um)
29	MinBGA pad center distance	Unit : mil	0.3
30	Interlaminar alignment	Unit : mil	±0.05mm(±0.002")
			The distance from the wall of via hole to the pattern